

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	SPD08N50C3	**Issued**	24. February 2022
MA#	MA005700070		
Package	PG-TO252-3-313	**Weight***	320.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.883	1.53	1.53	15253	15253
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		460	
	non noble metal	copper	7440-50-8	147.096	45.96	46.02	459524	460122
wire	non noble metal	aluminium	7429-90-5	0.666	0.21	0.21	2081	2081
encapsulation	inorganic material	zincoxide	1314-13-2	1.389	0.43		4341	
	miscellaneous	miscellaneous	-	6.947	2.17		21703	
	plastics	epoxy resin	-	20.842	6.51		65109	
	inorganic material	silicondioxide	60676-86-0	109.766	34.29	43.40	342907	434060
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11684	11684
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4438	4449
solder	non noble metal	tin	7440-31-5	0.079	0.02		247	
	noble metal	silver	7440-22-4	0.099	0.03		309	
	non noble metal	lead	7439-92-1	3.780	1.18	1.23	11807	12363
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59910	59988
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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